



LG-05IR4T94C-557U-B-T DATA SHEET

 SPEC. NO.
 :
 SZ21042902

 DATE
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 2021/04/29

 REV.
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 A/1

Approved By:

Checked By:

Prepared By:

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LIGHT ELECTRONICS CO., LTD.

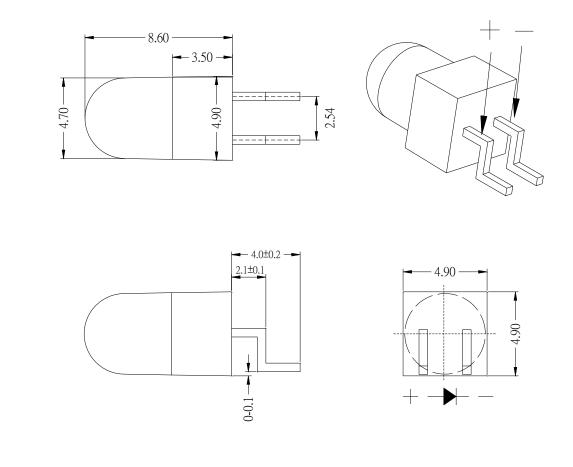
LIGHT

RoH9

Features

- Pb free product—RoHS compliant
- Low power consumption, High efficiency
- General purpose leads
- Reliable and rugged
- Long life solid state reliability
- ♦ Radiant angle: 27 °

Package Dimension



Part NO.	Chip Material	Lens Color
LG-05IR4T94C-557U-B-T	AlGaAs	Water Clear

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.20 mm unless otherwise noted.
- 3. Protruded resin under flange is 1.0mm max.
- 4. Lead spacing is measured where the leads emerge from the package.
- 5. Specifications are subject to change without notice.

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Absolute Maximum Ratings at Ta=25℃

Parameter	MAX.	Unit	
Power Dissipation	85 mW		
Continuous Forward Current	50 mA		
Peak Forward Current ^{*3}	1.0	А	
Reverse Voltage	5	V	
Operating Temperature	-40°C to $+85^{\circ}\text{C}$		
Storage Temperature	-40° C to $+100^{\circ}$ C		
Lead Soldering Temperature [2mm From Body]	260° C for 3 Seconds		
IR Reflow Temperature	245°C for 30 seconds		

1. Storage:

The storage ambient for the LEDs should not exceed 30 °C temperature or 70% relative humidity.

It is recommended that LEDs out of their original packaging are used within three months.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant or in desiccators with nitrogen ambient.

2. Precautions in handling:

- When soldering, leave 2mm of minimum clearance from the resin to the soldering point.
- Dipping the resin to solder must be avoided.
- Correcting the soldered position after soldering must be avoided.
- In soldering, do not apply any stress to the lead frame particularly when heated.
- When forming a lead, make sure not to apply any stress inside the resin.
- Lead forming must be done before soldering.
- It is necessary to cut the lead frame at normal temperature.

3. Peak Forward Current:

Condition for is IFP pulse : Pulse Width ≤ 0.1 ms and duty ≤ 1 %.

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Electrical Optical Characteristics at Ta=25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Radiant Intensity	Ie	70	100		mW/sr	I _F =50mA (Note 1,3)
Viewing Angle	$2\theta_{1/2}$	22	27	32	deg	(Note 2)
Peak Wavelength	λp		940		nm	I _F =20mA
Spectral Line Half- Width	Δλ		50		nm	I _F =20mA
Forward Voltage	$V_{\rm F}$		1.35	1.65	V	I _F =50mA
Reverse Current	I _R			100	μΑ	V _R =5V

Note:

- 1. Point sources of the amount of radiation per unit time in a given direction within the unit solid Angle radiated energy.
- 2. $\theta_{1/2}$ is the off-axis angle at which the Radiant Intensity is half the axial Radiant Intensity.
- 3. The Ie guarantee should be added $\pm 15\%$ tolerance.

Infrared Emitting Diode Specification

•Commodity: Infrared emitting diode

●Intensity Bin Limits (At 50mA)

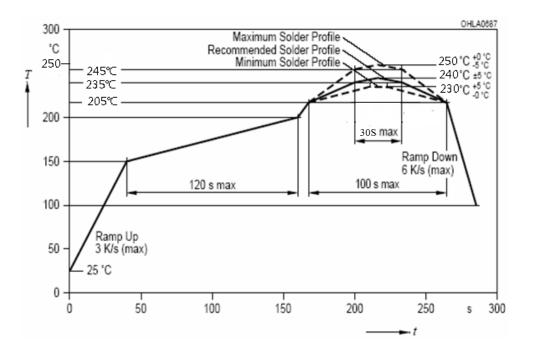
BIN CODE	Min.(mW/sr)	Max.((mW/sr)
38	70	98
39	98	137

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Suggest IR Reflow Condition For Lead Free:

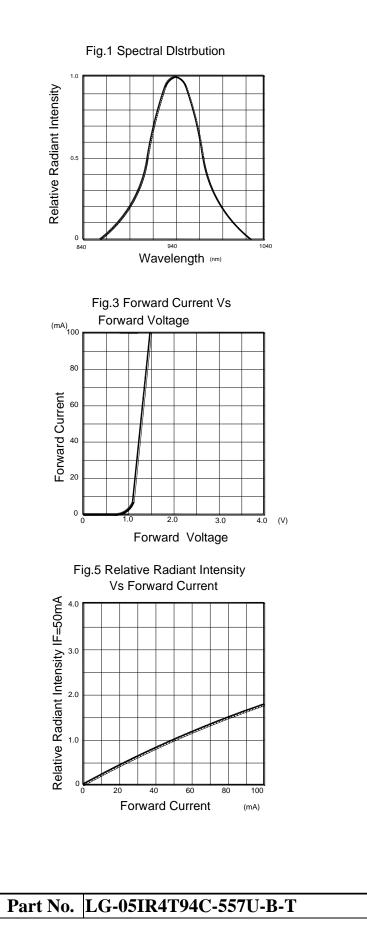


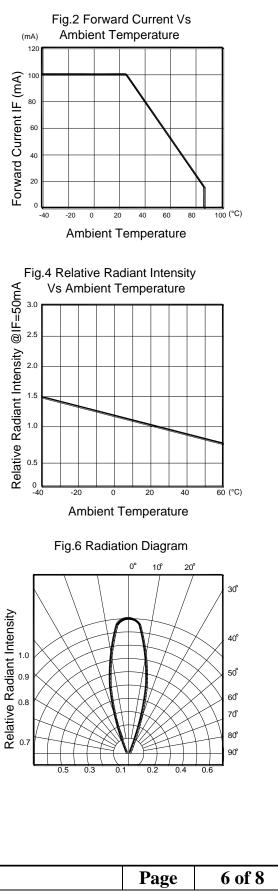
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Typical Electrical / Optical Characteristics Curves (25°C Ambient Temperature Unless Otherwise Noted)

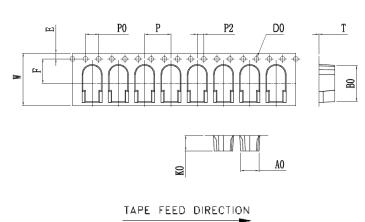


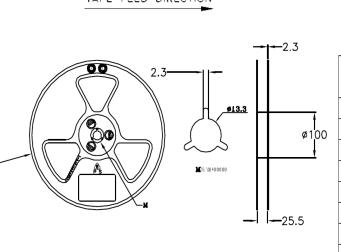




Package

Package Dimensions





Item	Specifi	cation
Item	Minmum	Maximum
W	15.97	16.3
р	7.9	8.1
E	1.65	1.85
F	7.4	7.6
D	1.5	1.6
PO	3.9	4.1
P0x10	39.8	40.2
P2	1.9	2.1
A0	5.2	5.4
BO	10.6	10.8
КО	4.8	5.0

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Notes:

Φ**380**

- 1.All dimensions in millimeters.
- 2.All dimensions meet EIA-481-C requirements.
- 3.Cover tape by a heat sealing manner.

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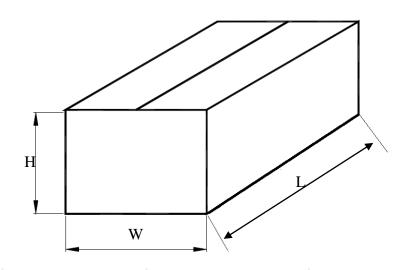
LIGHT



Package Spec:

1.2000pcs per reel.

15 reel per carton/Total 30000pcs per carton.



Itom	Specification		
Item	minmum	Maximum	
L	465	475	
W	405	415	
H	405	415	

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